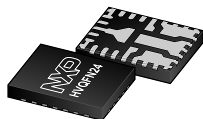
SOT2090-1(SC)

HWQFN24, thermal enhanced, very-very thin quad flat package, no leads, 24 terminals, step-cut wettable flank, 0.5 mm pitch, 3.5 mm x 4.5 mm x 0.68 mm body

5 October 2023 | Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN24
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-08-2023
Manufacturer package code	98ASA01654D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.4	3.5	3.6	mm
package width	4.4	4.5	4.6	mm
seated height	-	0.68	0.75	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	

2 Package outline

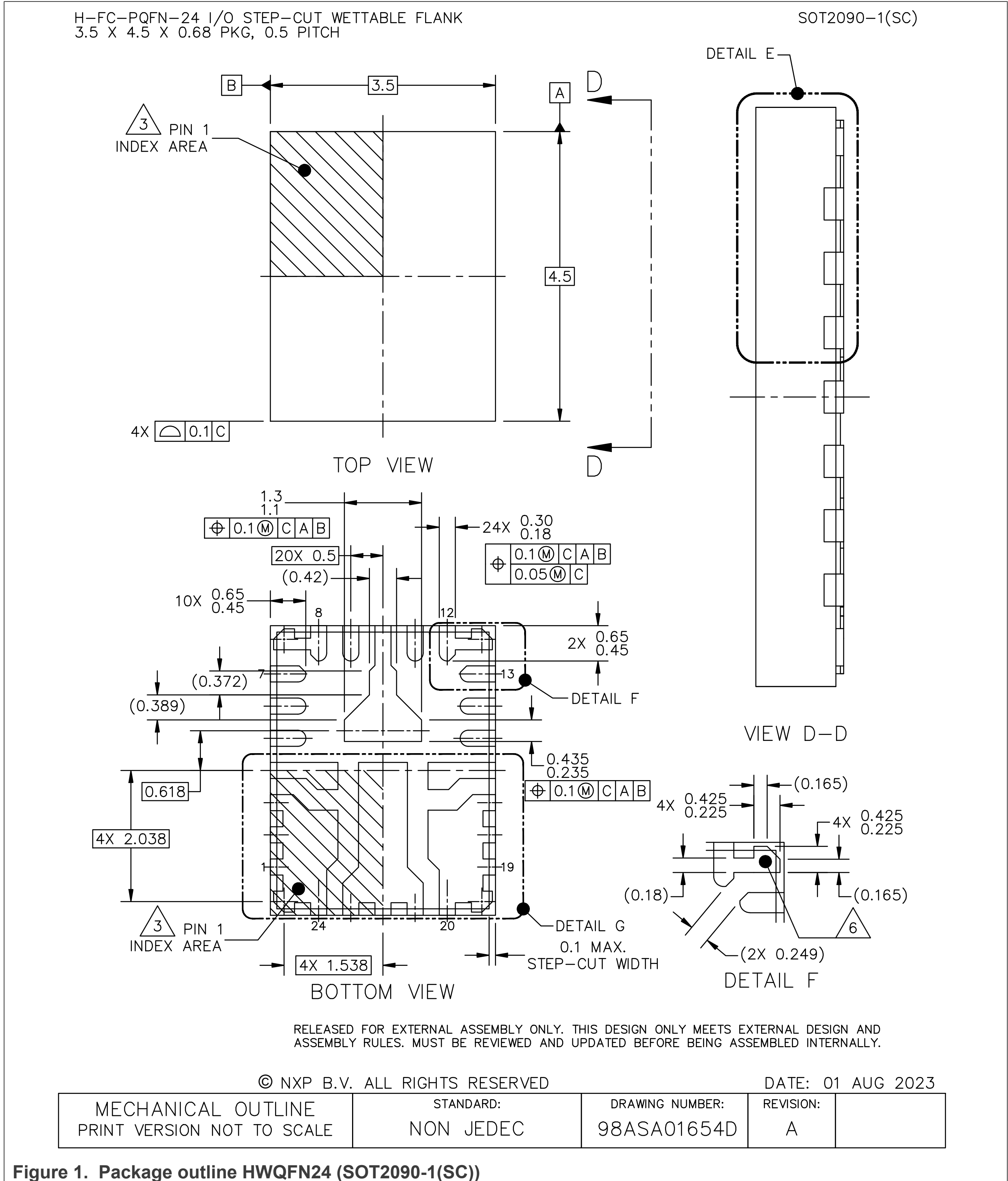


Figure 1. Package outline HWQFN24 (SOT2090-1(SC))

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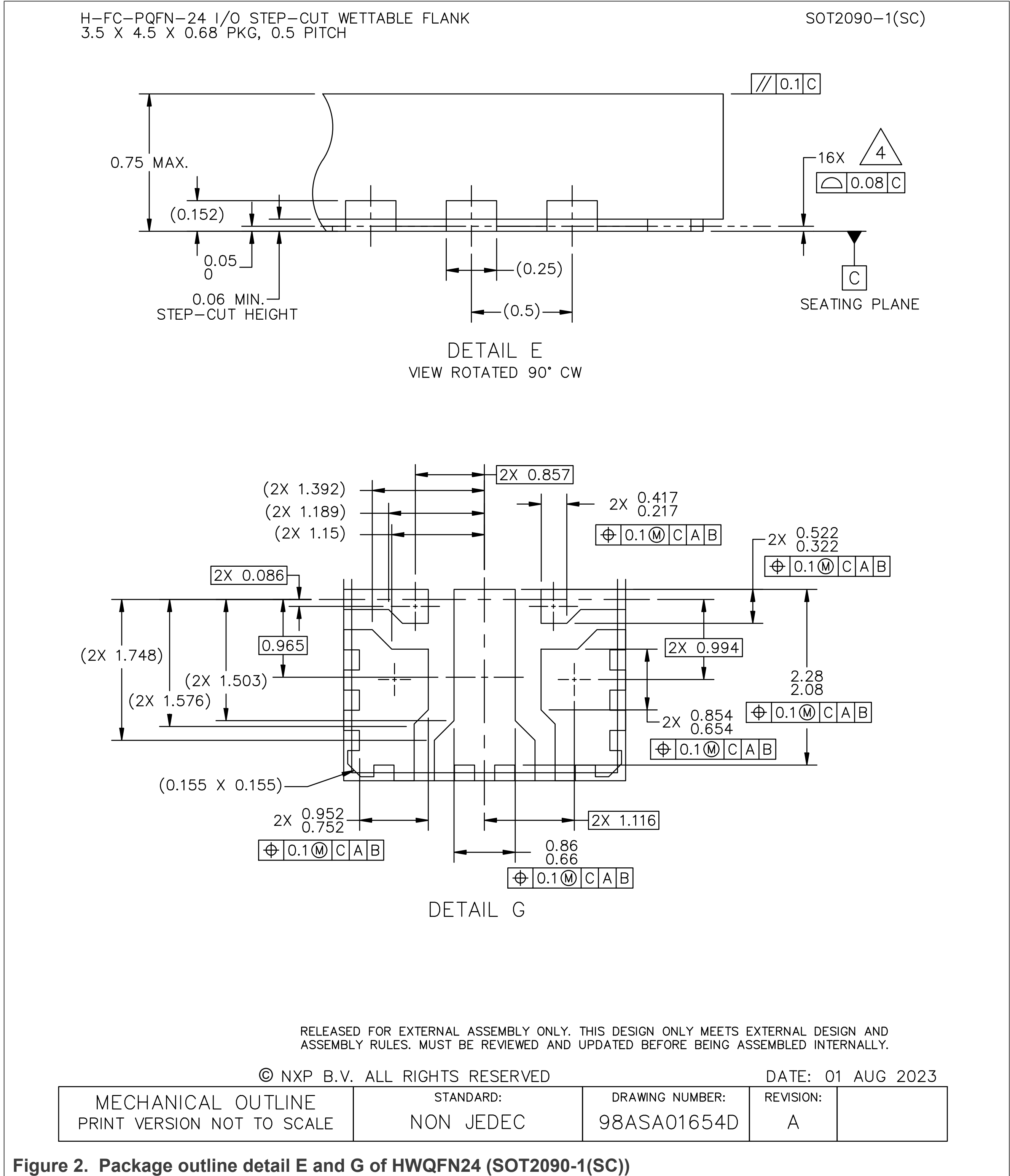

Figure 2. Package outline detail E and G of HWQFN24 (SOT2090-1(SC))

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3 Soldering

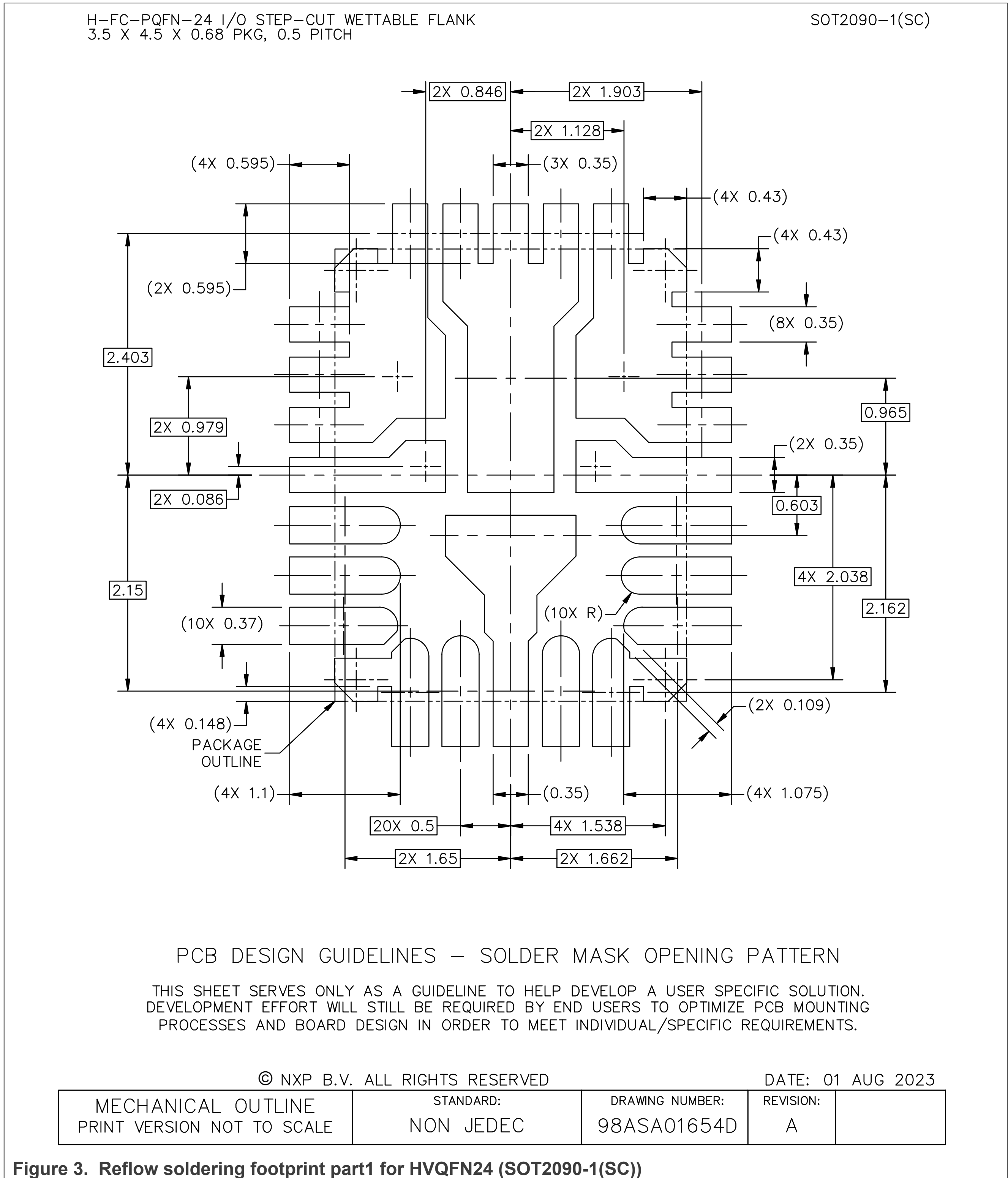

Figure 3. Reflow soldering footprint part1 for HVQFN24 (SOT2090-1(SC))

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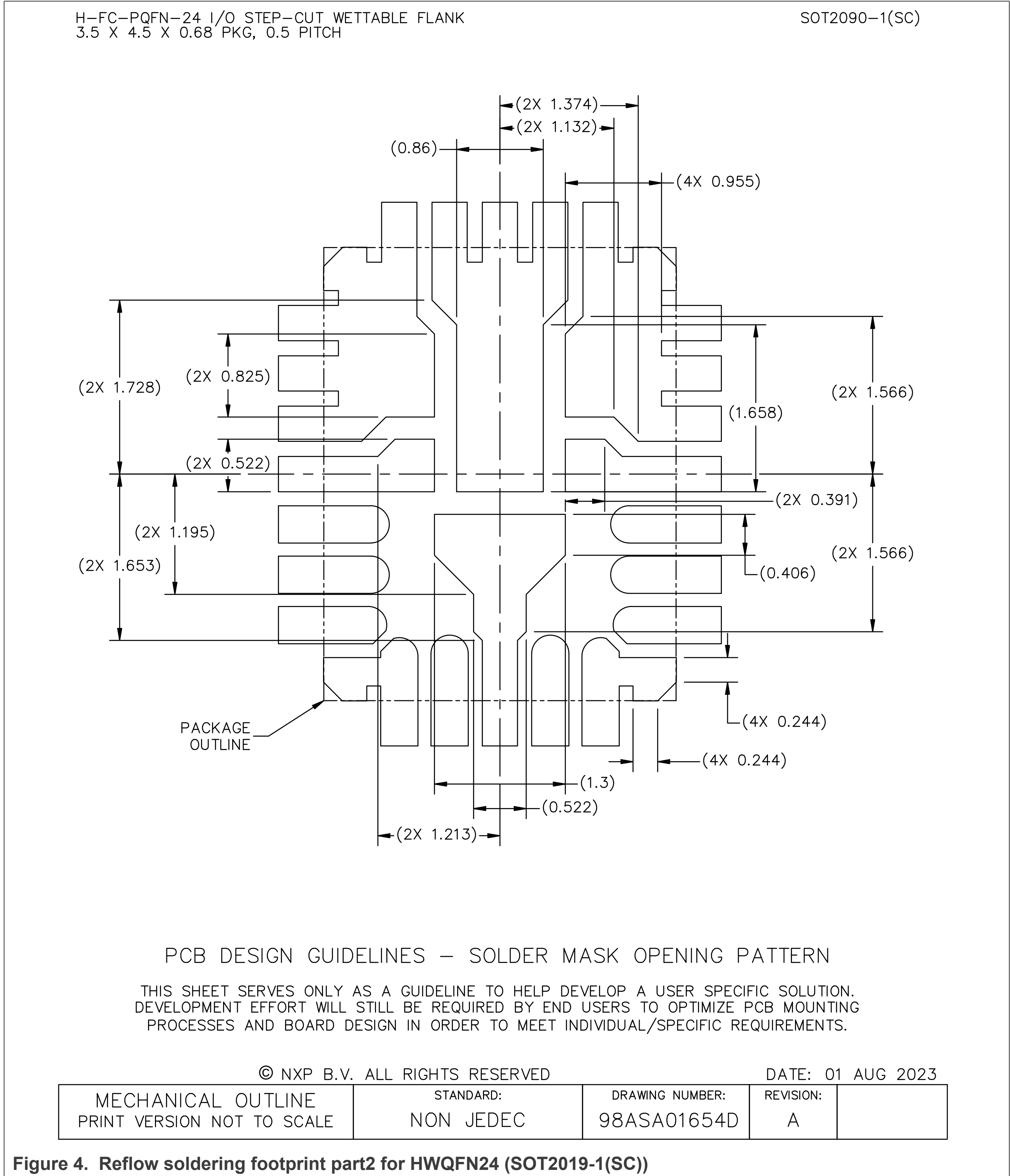

Figure 4. Reflow soldering footprint part2 for HWQFN24 (SOT2019-1(SC))

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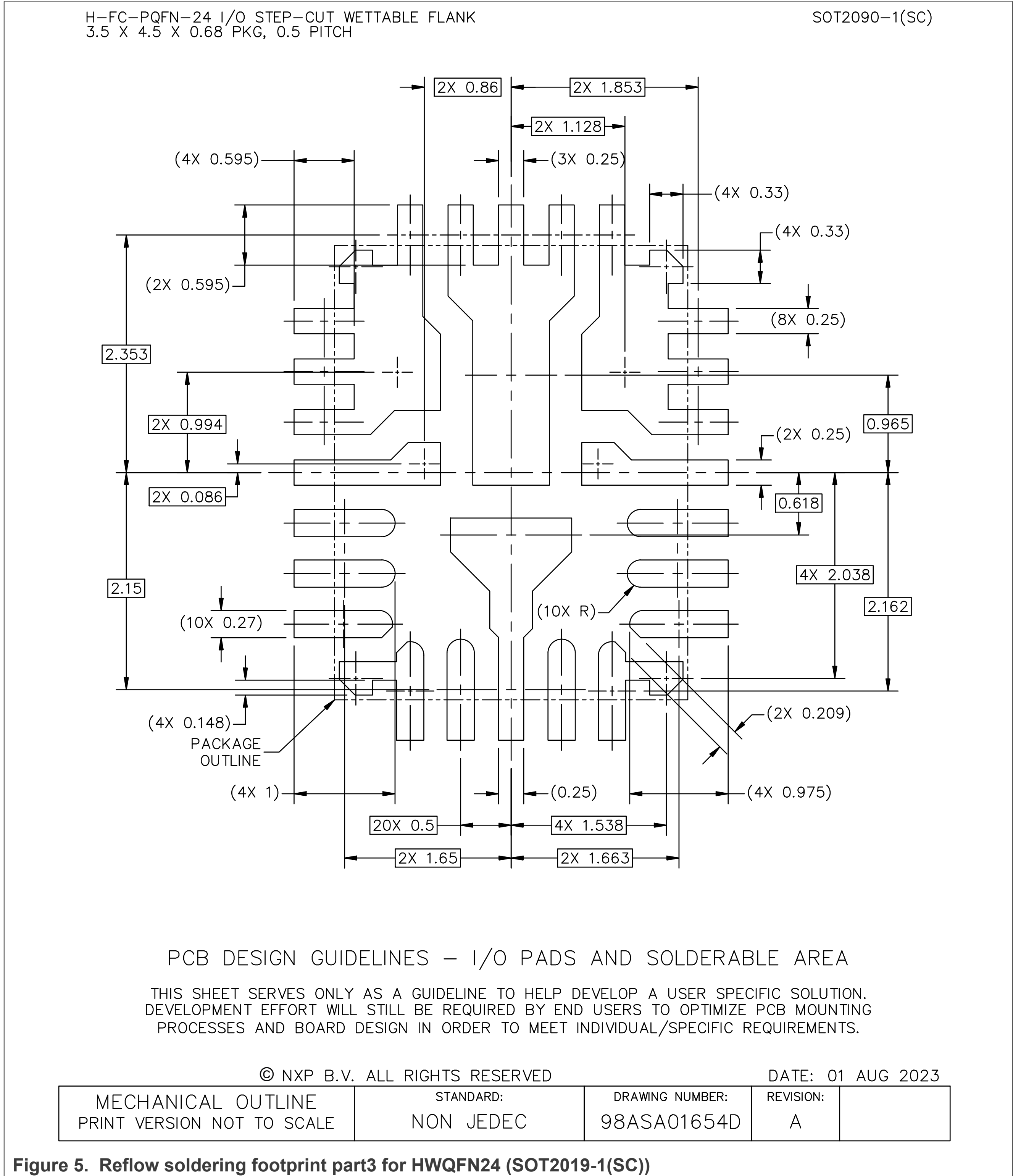

Figure 5. Reflow soldering footprint part3 for HWQFN24 (SOT2019-1(SC))

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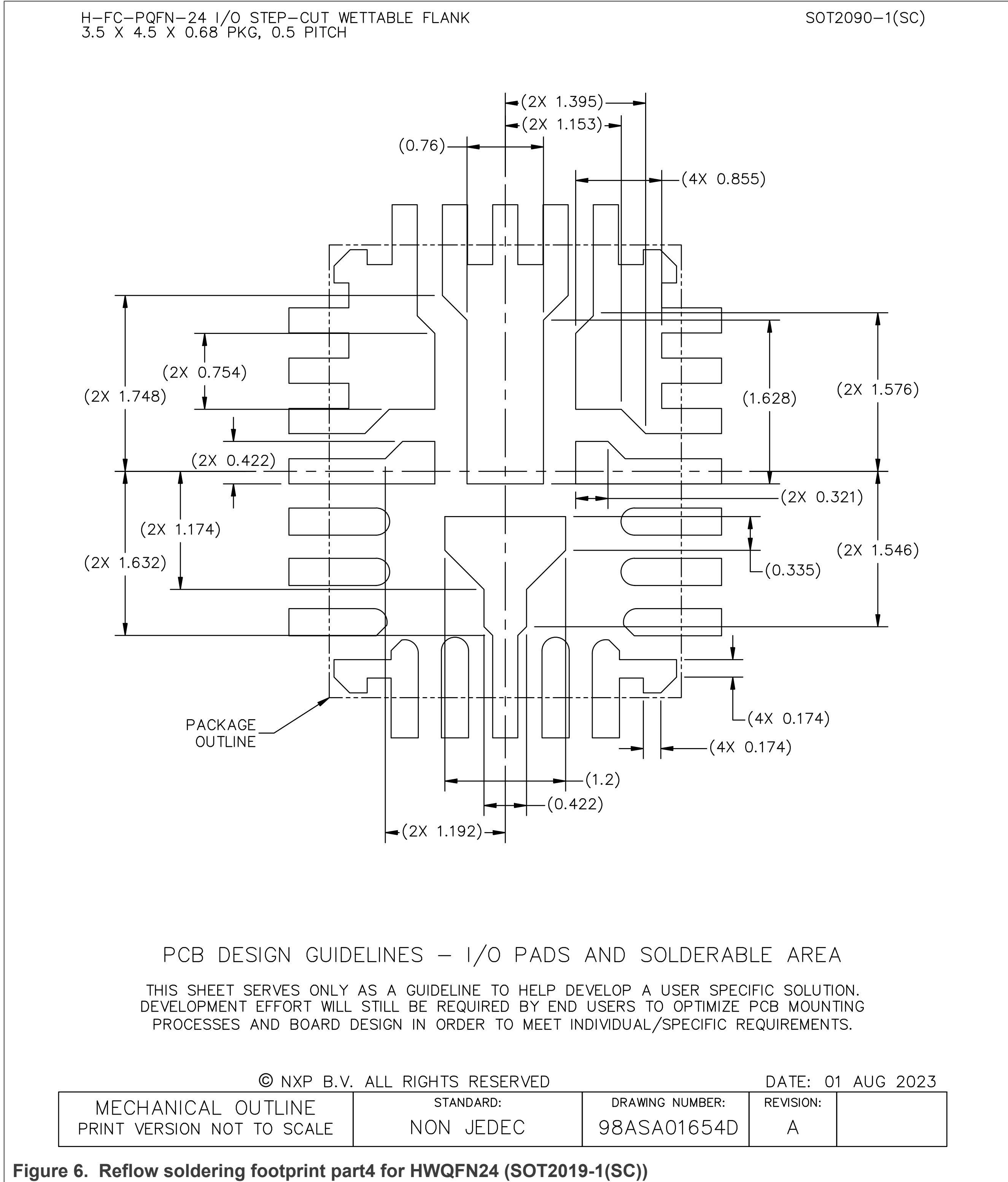

Figure 6. Reflow soldering footprint part4 for HWQFN24 (SOT2019-1(SC))

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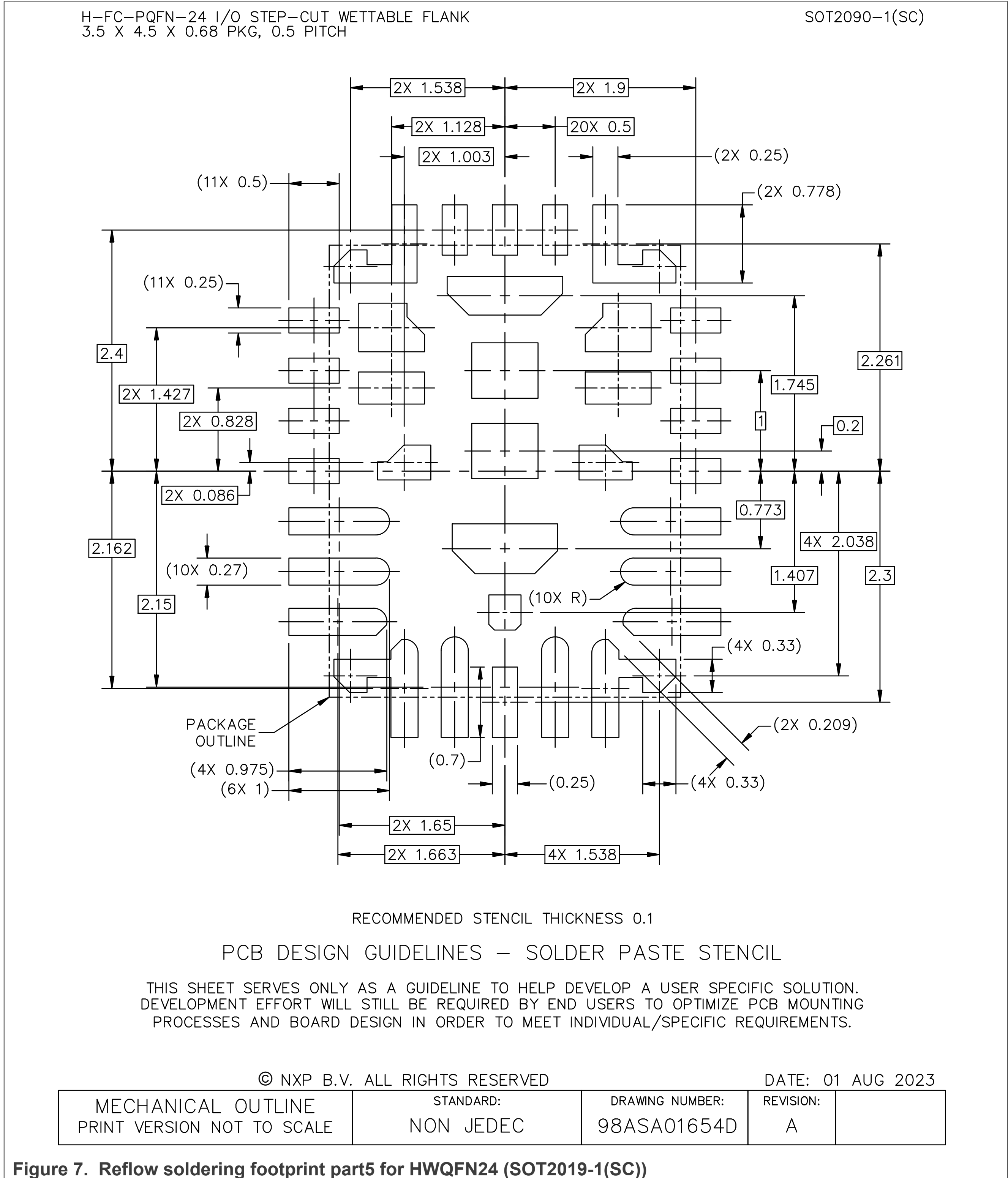

Figure 7. Reflow soldering footprint part5 for HWQFN24 (SOT2019-1(SC))

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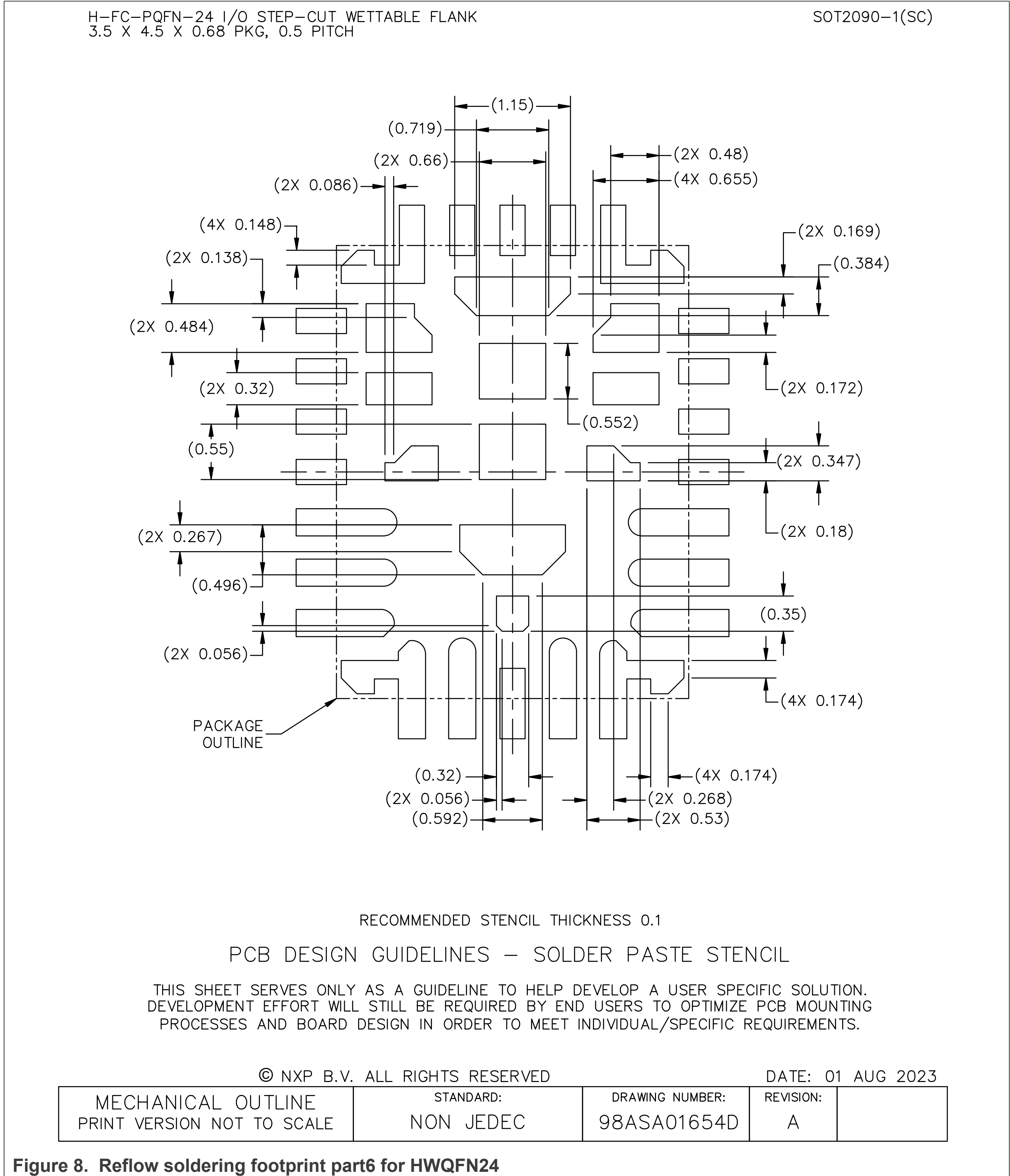

Figure 8. Reflow soldering footprint part6 for HWQFN24

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H-FC-PQFN-24 I/O STEP-CUT WETTABLE FLANK
3.5 X 4.5 X 0.68 PKG, 0.5 PITCH

SOT2090-1(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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DATE: 01 AUG 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01654D	REVISION: A	

Figure 9. Package outline note HWQFN24 (SOT2019-1(SC))

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4 Legal information

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Date of release: 5 October 2023